

## Dual N-Ch 40V Fast Switching MOSFETs

- ★ Green Device Available
- ★ Super Low Gate Charge
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology

## Product Summary



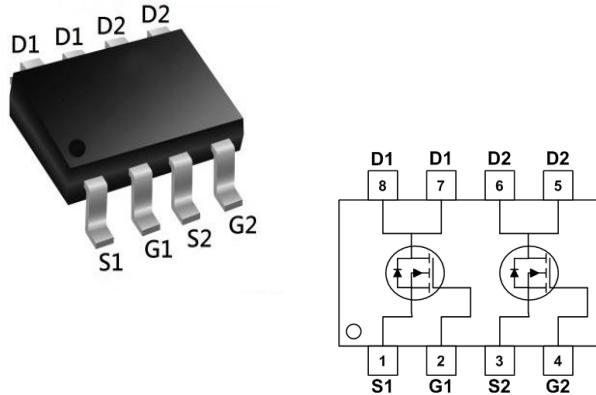
BVDSS	RDS(ON)	ID
40V	14mΩ	12A

## Description

The XR4884B is the high cell density trenched N-ch MOSFETs, which provides excellent RDS(ON) and efficiency for most of the small power switching and load switch applications.

The XR4884B meet the RoHS and Green Product requirement with full function reliability approved.

## SOP8 Pin Configuration

Absolute Maximum Ratings (@  $T_J = 25^\circ\text{C}$  unless otherwise specified)

Symbol	Parameter	Value	Units
$V_{DS}$	Drain-to-Source Voltage	40	V
$V_{GS}$	Gate-to-Source Voltage	$\pm 20$	V
$I_D$	Continuous Drain Current $T_C = 25^\circ\text{C}$	20	A
		12	
$I_{DM}$	Pulsed Drain Current <sup>(1)</sup>	80	A
$E_{AS}$	Single Pulsed Avalanche Energy <sup>(2)</sup>	28	mJ
$P_D$	Power Dissipation $T_C = 25^\circ\text{C}$	12.5	W
$R_{\theta JC}$	Thermal Resistance, Junction to Case	10.0	$^\circ\text{C}/\text{W}$
$T_J, T_{STG}$	Junction & Storage Temperature Range	-55 to 150	$^\circ\text{C}$

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Electrical Characteristics ( $T_J = 25^\circ\text{C}$  unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
<b>Off Characteristics</b>						
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$I_D = 250\mu\text{A}, V_{GS} = 0\text{V}$	40	-	-	V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS} = 40\text{V}, V_{GS} = 0\text{V}$	-	-	1.0	$\mu\text{A}$
$I_{GSS}$	Gate-Body Leakage Current	$V_{DS} = 0\text{V}, V_{GS} = \pm 20\text{V}$	-	-	$\pm 100$	nA
<b>On Characteristics</b>						
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	1.0	1.4	2.0	V
$R_{DS(\text{ON})}$	Static Drain-Source ON-Resistance <sup>(3)</sup>	$V_{GS} = 10\text{V}, I_D = 10\text{A}$	-	14.0	19.5	$\text{m}\Omega$
		$V_{GS} = 4.5\text{V}, I_D = 8\text{A}$	-	17.7	22.6	$\text{m}\Omega$
<b>Dynamic Characteristics</b>						
$C_{iss}$	Input Capacitance	$V_{GS} = 0\text{V}, V_{DS} = 20\text{V}, f = 1\text{MHz}$	-	850	-	pF
$C_{oss}$	Output Capacitance		-	78	-	pF
$C_{rss}$	Reverse Transfer Capacitance		-	69	-	pF
$Q_g$	Total Gate Charge	$V_{GS} = 0 \text{ to } 10\text{V}$ $V_{DS} = 20\text{V}, I_D = 10\text{A}$	-	12	-	nC
$Q_{gs}$	Gate Source Charge		-	2	-	nC
$Q_{gd}$	Gate Drain("Miller") Charge		-	2.5	-	nC
<b>Switching Characteristics</b>						
$t_{d(on)}$	Turn-On Delay Time	$V_{GS} = 10\text{V}, V_{DD} = 20\text{V}$ $I_D = 10\text{A}, R_{GEN} = 3\Omega$	-	10	-	ns
$t_r$	Turn-On Rise Time		-	12	-	ns
$t_{d(off)}$	Turn-Off Delay Time		-	33	-	ns
$t_f$	Turn-Off Fall Time		-	9	-	ns
<b>Drain-Source Diode Characteristics and Max Ratings</b>						
$I_s$	Maximum Continuous Drain to Source Diode Forward Current	-	-	20	-	A
$I_{SM}$	Maximum Pulsed Drain to Source Diode Forward Current	-	-	80	-	A
$V_{SD}$	Drain to Source Diode Forward Voltage	$V_{GS} = 0\text{V}, I_s = 15\text{A}$	-	-	1.2	V
$trr$	Body Diode Reverse Recovery Time	$I_F = 10\text{A}, dI/dt = 100\text{A}/\mu\text{s}$	-	17	-	ns
$Qrr$	Body Diode Reverse Recovery Charge		-	10	-	nC

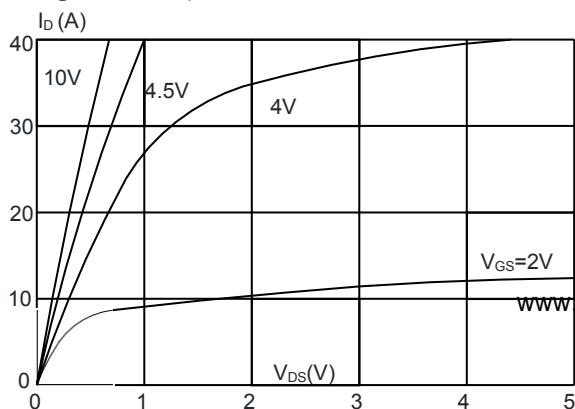
Notes:

1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.

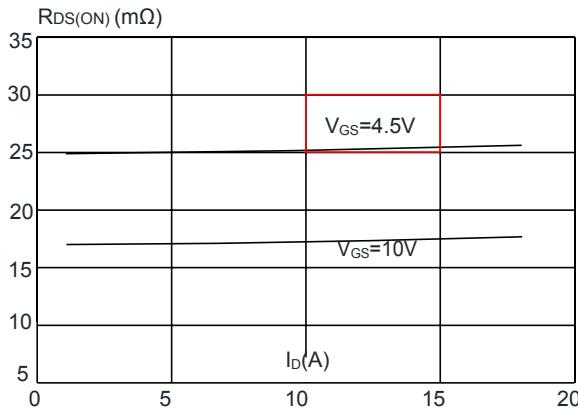
2. E<sub>AS</sub> condition: Starting  $T_J=25^\circ\text{C}$ ,  $V_{DD}=20\text{V}$ ,  $V_G=10\text{V}$ ,  $R_G=25\text{ohm}$ ,  $L=0.5\text{mH}$ ,  $I_{AS}=10.5\text{A}$ 3. Pulse Test: Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 0.5\%$ .

## Typical Performance Characteristics-N

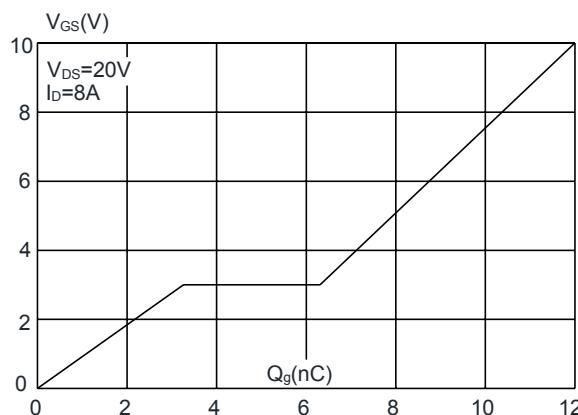
**Figure 1:** Output Characteristics



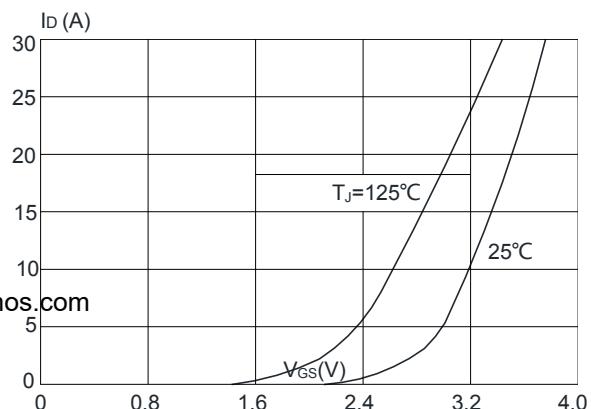
**Figure 3:** On-resistance vs. Drain Current



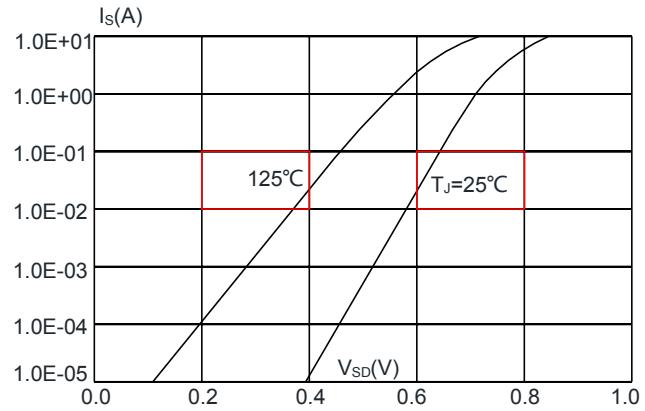
**Figure 5:** Gate Charge Characteristics



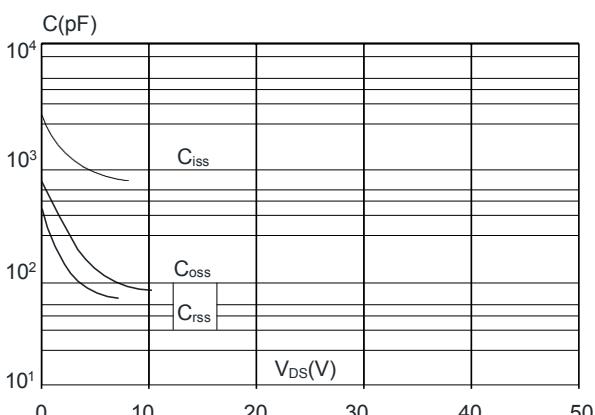
**Figure 2:** Typical Transfer Characteristics



**Figure 4:** Body Diode Characteristics

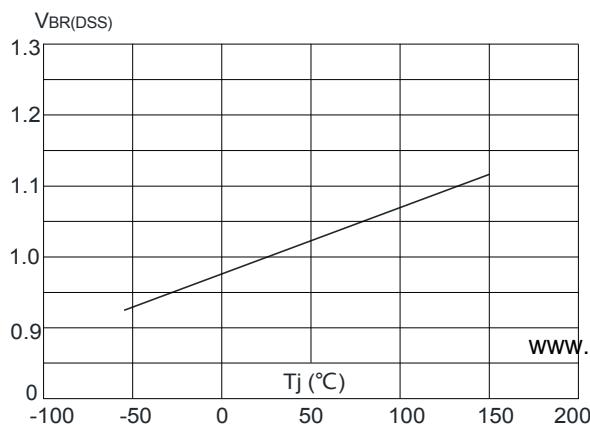


**Figure 6:** Capacitance Characteristics

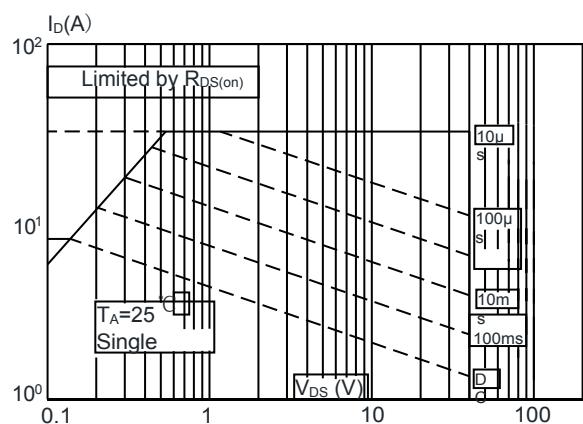


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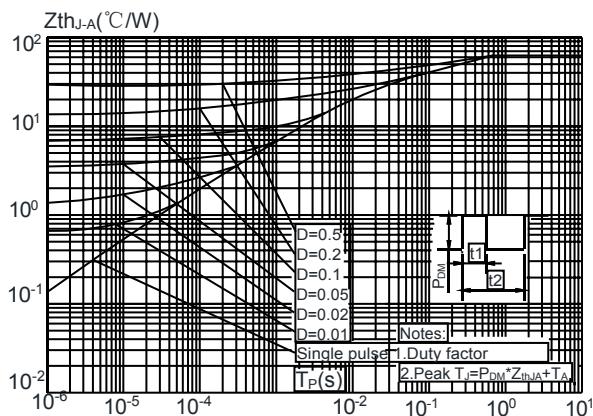
**Figure 7:** Normalized Breakdown Voltage vs. Junction Temperature



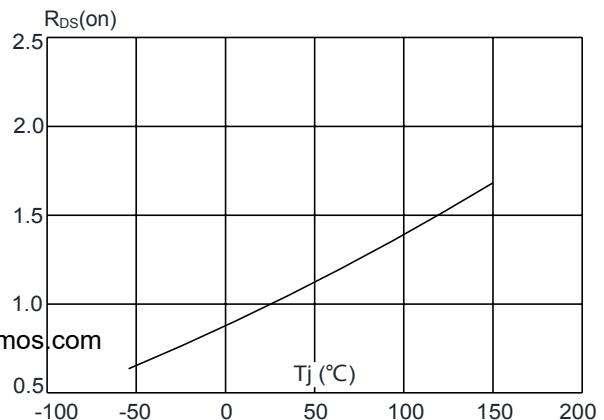
**Figure 9:** Maximum Safe Operating Area



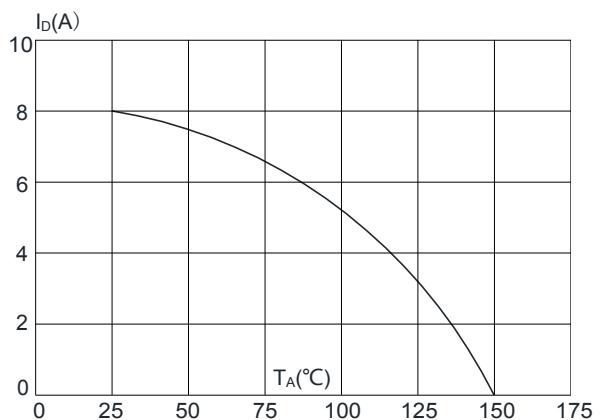
**Figure 11:** Maximum Effective Transient Thermal Impedance, Junction-to-Ambient



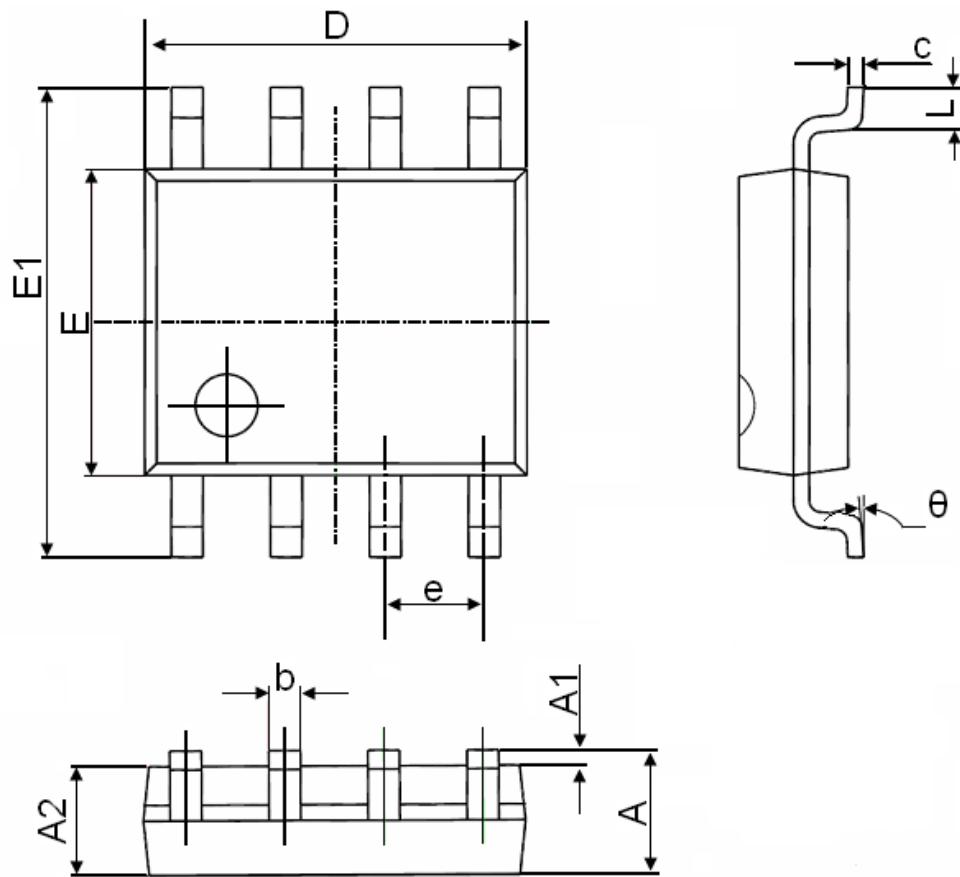
**Figure 8:** Normalized on Resistance vs. Junction Temperature



**Figure 10:** Maximum Continuous Drain Current vs. Ambient Temperature



## SOP-8 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270(BSC)		0.050(BSC)	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°